

# N-Channel 20-V (D-S) MOSFET

| PRODUCT SUMMARY          |                                 |                                 |  |  |
|--------------------------|---------------------------------|---------------------------------|--|--|
| V <sub>(BR)DSS</sub> (V) | $r_{DS(on)}\left(\Omega\right)$ | I <sub>D</sub> (A) <sup>a</sup> |  |  |
| 20                       | 0.004@ V <sub>GS</sub> = 4.5 V  | 100                             |  |  |
|                          | 0.005@ V <sub>GS</sub> = 2.5 V  | 95                              |  |  |

**TO-220AB** 

Top View

#### **FEATURES**

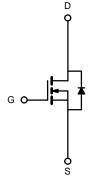


- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
   Compliant to RoHS Directive 2011/65/EU

#### **APPLICATIONS**

- OR-ing
- Server
- DC/DC

T<sub>J</sub>, T<sub>stg</sub>



-55 to 175

|  |                        |                 | N-Channel MOSFE  | Т        |
|--|------------------------|-----------------|------------------|----------|
| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25°C UNLESS OTHERWISE NOTED)  Parameter Symbol Limit Unit |                        |                 |                  |          |
| Drain-Source Voltage   | V <sub>DS</sub>        | 20              | V                |          |
| Gate-Source Voltage  |                        | V <sub>GS</sub> | ±12              | <b>–</b> |
| Continuous Drain Current (T <sub>.1</sub> = 175°C)   | T <sub>C</sub> = 25°C  | , 10            | 100              |          |
| Continuous Diam Curient (1) = 175 C)   | T <sub>C</sub> = 100°C | l <sub>D</sub>  | 85               |          |
| Pulsed Drain Current   |                        | I <sub>DM</sub> | 260              | A        |
| Avalanche Current  |                        | I <sub>AR</sub> | 35               |          |
| Repetitive Avalanche Energy <sup>b</sup>   | L = 0.1 mH             | E <sub>AR</sub> | 45               | mJ       |
| Power Dissipation  | T <sub>C</sub> = 25°C  | Pn              | 125 <sup>a</sup> | w        |

| THERMAL RESISTANCE RATINGS |                                 |                   |      |      |  |  |
|----------------------------|---------------------------------|-------------------|------|------|--|--|
| Parameter                  | Symbol                          | Limit             | Unit |      |  |  |
| Junction-to-Ambient        | PCB Mount (TO-263) <sup>c</sup> | $R_{thJA}$        | 40   | °C/W |  |  |
| Junction-to-Ambient        | Free Air (TO-220AB)             |                   | 62.5 |      |  |  |
| Junction-to-Case           |                                 | R <sub>thJC</sub> | 1.25 |      |  |  |

#### Notes:

- See SOA curve for voltage derating.
- Duty cycle ≤ 1%. When mounted on 1" square PCB (FR-4 material).

Operating Junction and Storage Temperature Range

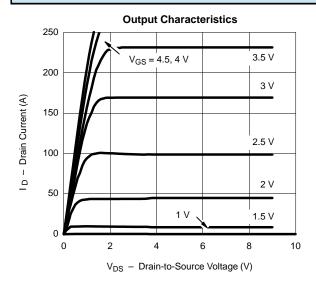


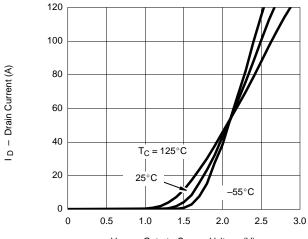
| Parameter                                     | Symbol               | Test Condition   | Min | Тур   | Max  | Unit |  |
|---|----------------------|--|-----|-------|------|------|--|
| Static  |                      |  | •   | •     |      |      |  |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub> | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$                            | 20  |       |      | V    |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_{DS} = 250 \mu A$                                    | 0.5 |       | 1.5  | ľ    |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS}$ = 0 V, $V_{GS}$ = $\pm$ 12 V                                    |     |       | ±100 | nA   |  |
|   |                      | $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$                            |     |       | 1    |      |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>     | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125°C    |     |       | 50   | μΑ   |  |
|   |                      | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175°C    |     |       | 150  |      |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$                           | 120 |       |      | Α    |  |
|   |                      | $V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}$                             |     | 0.004 |      |      |  |
| Drain Source On State Begintance              | 「DS(on)              | $V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}, T_J = 125 ^{\circ}\text{C}$ |     | 0.007 |      | Ω    |  |
| Drain-Source On-State Resistance <sup>a</sup> |                      | $V_{GS} = 4.5 \text{ V}, I_D = 30 \text{ A}, T_J = 175^{\circ}\text{C}$  |     | 0.010 |      |      |  |
|   |                      | $V_{GS} = 2.5 \text{ V}, I_D = 20 \text{ A}$                             |     | 0.005 |      |      |  |
| Forward Transconductancea                     | 9fs                  | $V_{DS} = 5 \text{ V}, I_{D} = 30 \text{ A}$                             | 20  |       |      | S    |  |
| Dynamic <sup>b</sup>                          |                      |  | •   | •     |      |      |  |
| Input Capacitance                             | C <sub>iss</sub>     |  |     | 6000  |      | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>     | $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$         |     | 1100  |      |      |  |
| Reversen Transfer Capacitance                 | C <sub>rss</sub>     |  |     | 600   |      | 1    |  |
| Total Gate Charge <sup>c</sup>                | Qg                   |  |     | 65    | 130  | nC   |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>      | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 85 \text{ A}$      |     | 13    |      |      |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>      |  |     | 14    |      | 1    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |  |     | 25    | 40   | ns   |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD}$ = 10 V, $R_L$ = 0.12 $\Omega$                                   |     | 120   | 180  |      |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | $I_D \simeq 85$ A, $V_{GEN} = 4.5$ V, $R_G = 2.5~\Omega$                 |     | 80    | 120  |      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |  |     | 100   | 150  |      |  |
| Source-Drain Diode Ratings a                  | nd Characteristic    | es (T <sub>C</sub> = 25°C)b  |     |       |      |      |  |
| Pulsed Current                                | I <sub>SM</sub>      |  |     |       | 240  | А    |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | $I_F = 100 \text{ A}, V_{GS} = 0 \text{ V}$                              |     | 1.2   | 1.5  | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      | $I_F = 50 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$ 45       |     | 100   | ns   |      |  |

- Notes: a. Pulse test; pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2\%$ . b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.

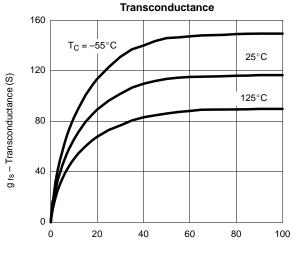


### TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

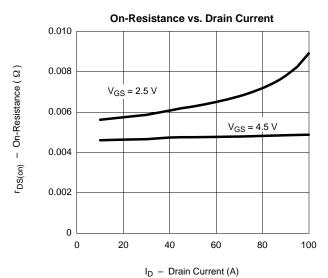




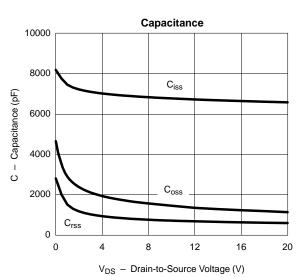
**Transfer Characteristics** 



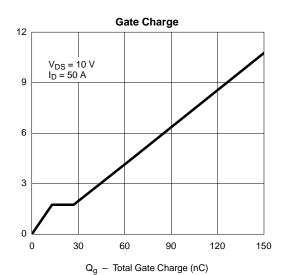
V<sub>GS</sub> - Gate-to-Source Voltage (V)



I<sub>D</sub> - Drain Current (A)

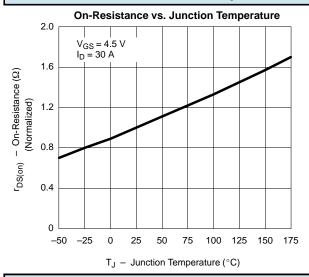


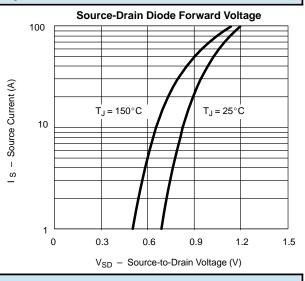




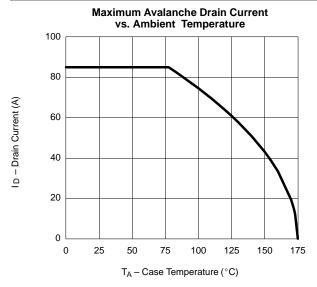


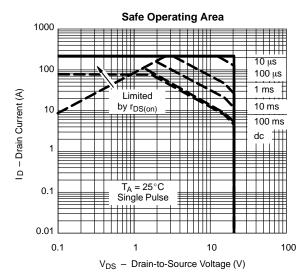
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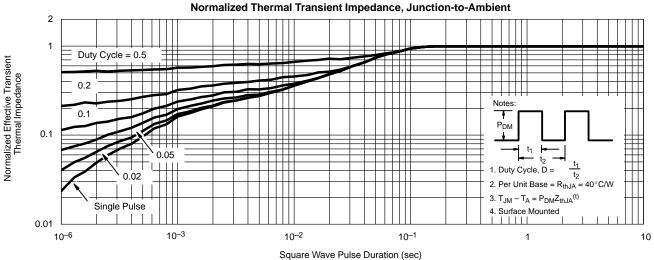




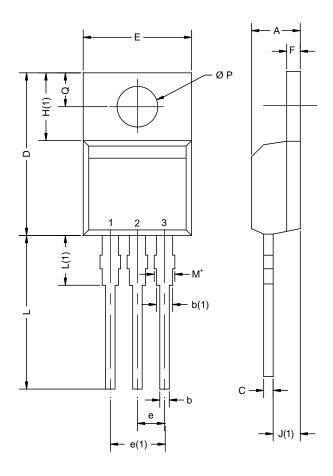
#### THERMAL RATINGS







## **TO-220AB**



|  | MILLIMETERS |       | INC   | HES   |
|--|-------------|-------|-------|-------|
| DIM.   | MIN.        | MAX.  | MIN.  | MAX.  |
| Α  | 4.25        | 4.65  | 0.167 | 0.183 |
| b  | 0.69        | 1.01  | 0.027 | 0.040 |
| b(1)   | 1.20        | 1.73  | 0.047 | 0.068 |
| С  | 0.36        | 0.61  | 0.014 | 0.024 |
| D  | 14.85       | 15.49 | 0.585 | 0.610 |
| Е  | 10.04       | 10.51 | 0.395 | 0.414 |
| е  | 2.41        | 2.67  | 0.095 | 0.105 |
| e(1)   | 4.88        | 5.28  | 0.192 | 0.208 |
| F  | 1.14        | 1.40  | 0.045 | 0.055 |
| H(1)   | 6.09        | 6.48  | 0.240 | 0.255 |
| J(1)   | 2.41        | 2.92  | 0.095 | 0.115 |
| L  | 13.35       | 14.02 | 0.526 | 0.552 |
| L(1)   | 3.32        | 3.82  | 0.131 | 0.150 |
| ØР   | 3.54        | 3.94  | 0.139 | 0.155 |
| Q  | 2.60        | 3.00  | 0.102 | 0.118 |
| ECN: X12-0208-Rev. N, 08-Oct-12<br>DWG: 5471 |             |       |       |       |

#### Notes

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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